



Tracking Technologies and Muon ID for the 2nd EIC Detector

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05-09-2024

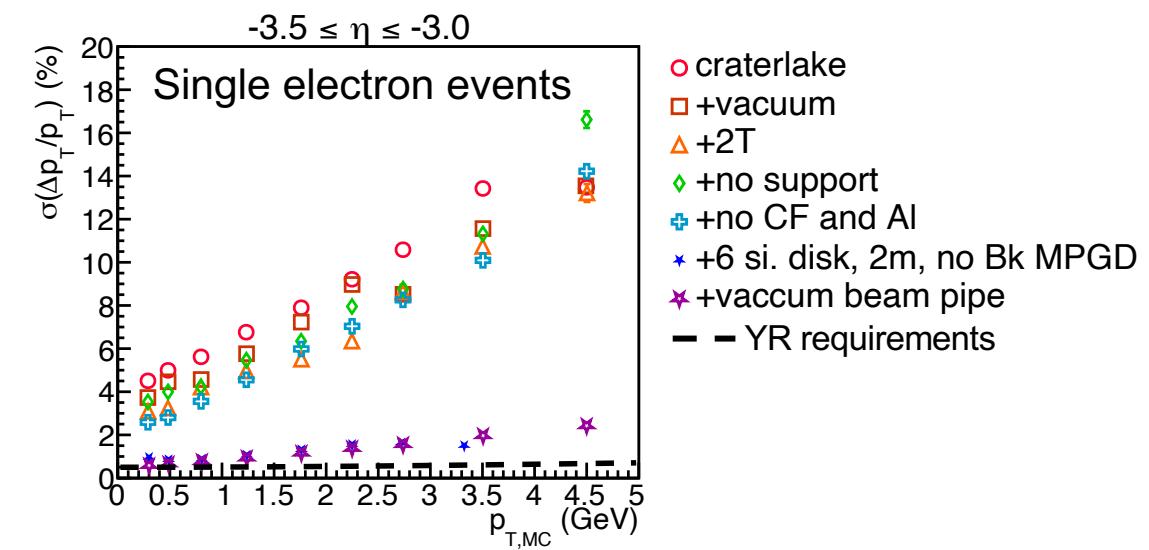
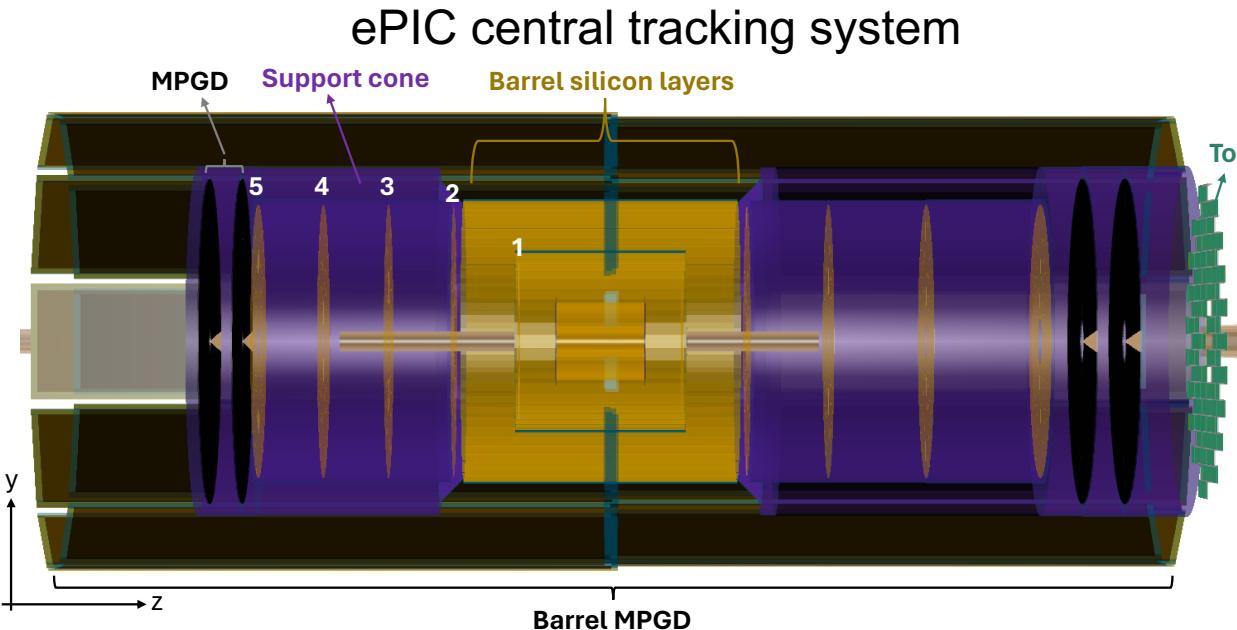


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Backward Tracking

- Scattered electron measurement is essential in EIC to obtain Q^2
 - More backward, lower Q^2
- Can I optimize the ePIC silicon tracking system to achieve p_T resolution $<1\%$ (YR requirement) in the backward region?

Very challenging



New Direction

- Shifting the focus from an all-silicon design to a **mixed-tracking technologies** design
 - Pros: (1) More hits: better pattern recognition, redundancy, resistance against backgrounds
(2) Complementary
 - Cons: higher material budget
- Potential tracking technologies: scintillating fiber, drift chamber, TPC...
Other Suggestions are welcome!

Increasing the number of hits could improve tracking resolution

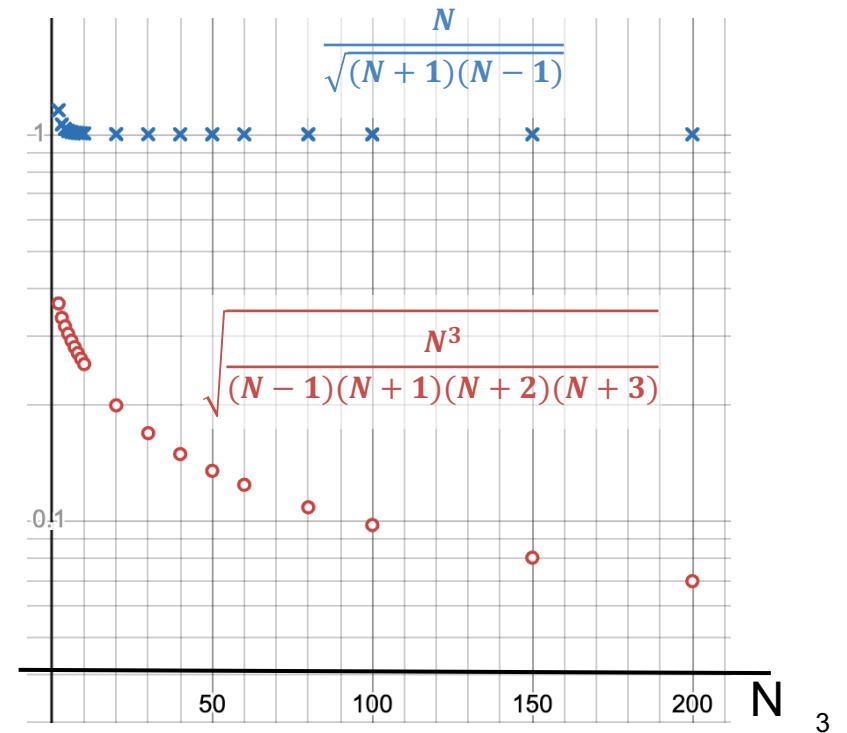
NIMA 910 (2018) 127

Resolution from detector pixel

$$\frac{\Delta p}{p_{res}} = \frac{\sigma_{pix} \cdot p}{0.3BL^2} \sqrt{\frac{720N^3}{(N-1)(N+1)(N+2)(N+3)}}$$

Resolution from multiple scattering

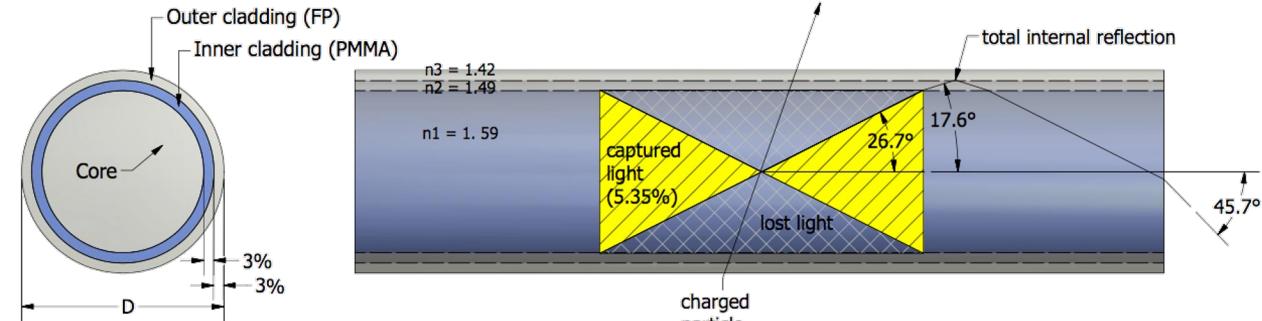
$$\frac{\Delta p}{p_{ms}} = \frac{N}{\sqrt{(N+1)(N-1)}} \frac{0.0136\sqrt{X/X_0}(1 + 0.038 \cdot \ln\sqrt{X/X_0})}{0.3BL \cdot \frac{p}{\sqrt{m^2 + p^2}}}$$



Scintillating Fiber (LHCb)

Double-clad polystyrene fiber

- $D=250 \text{ }\mu\text{m} \rightarrow \text{hit pos. res. } < 70 \text{ }\mu\text{m}$
- 8k photons per MeV of ionization energy
- Excited electron decay times=2.4 ns
- Attenuation length~3.5 m



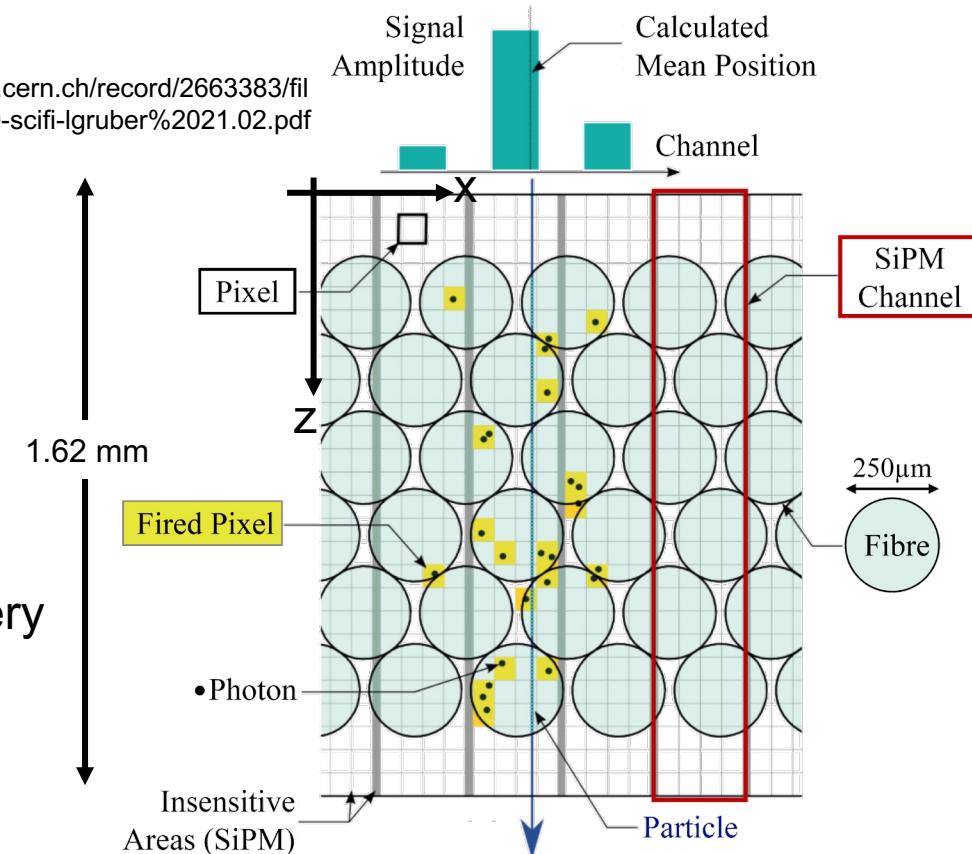
Hamamatsu SiPM (MPPC S13552 – H2017)

- Pixel size ~ 60 μm
- <10% noise cluster rate with front-end clustering and -50 °C cooling using Novec

Material budget= $1.1\% \times 12 \text{ layers}$

Technology advancement

- Scintillating fiber with improved radiation hardness
- Modify claddings to boost light yield
- Cryogenic cooled SiPMs with microlenses for light recovery



Drift Chamber (IDEA/MEG II)

Reduction of material

by storing helium gas in the wire support endplates

IDEA: $0.016X_0$ ($0.05X_0$) in the barrel (forward and backward) region

More uniform equipotential surface

A high ratio of the field to sense wires and a high wire density by enmeshes the positive and negative stereo angle orientations

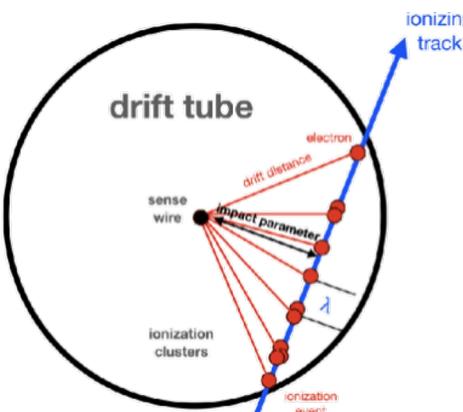
IDEA: 4 m long, $r = 35\text{-}200$ cm, 400k wires, res ~ 100 um

PID capability with the cluster counting method

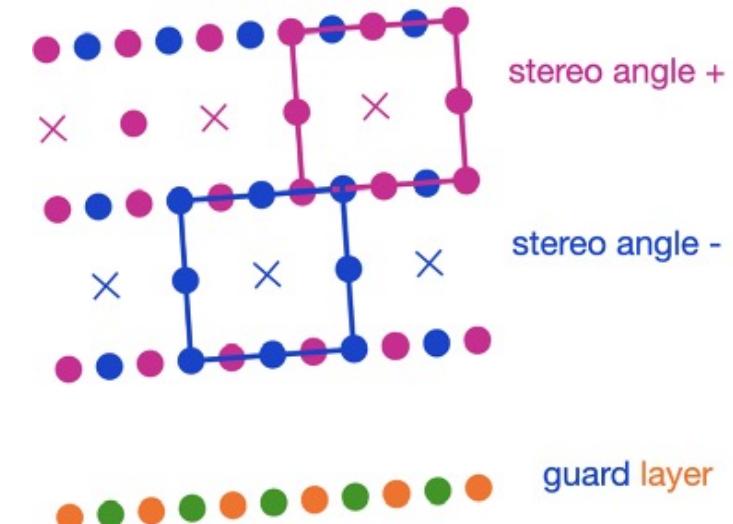
Adding timing information to the wires to count individual ionizing events of the traversing track and dE/dx information

Technology advancements

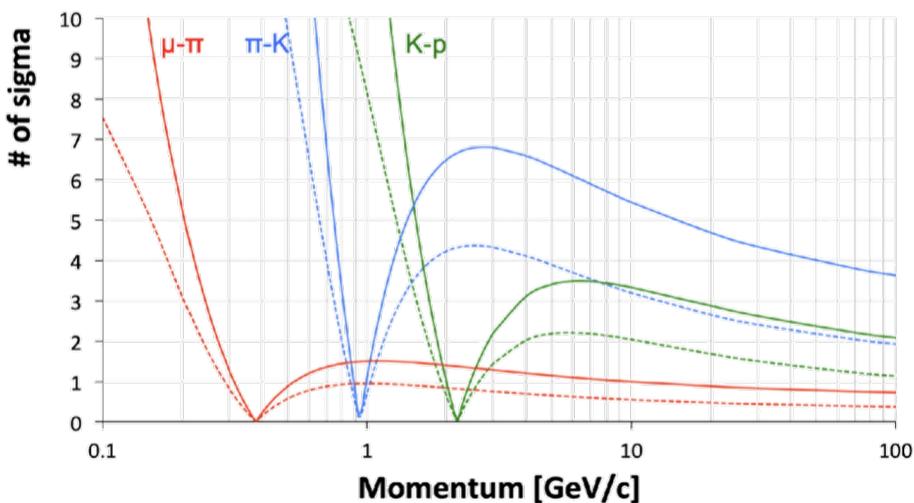
- Carbon-fiber wire vs tungsten wire
reduce X/X_0 by a factor of 5
- Low - mass service/cooling structures
- See Andy's slides from last week



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Particle Separation (dE/dx vs dN/dx)

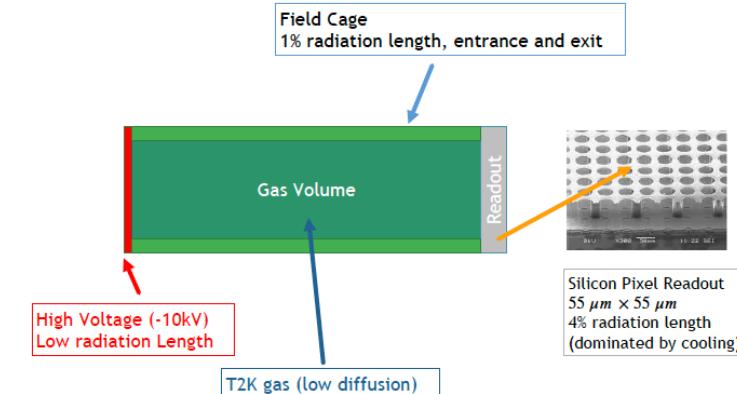


TPC/mini TPC

GridPIX aka miniTPC

- Basic idea: Small ΔR TPC with Si Pixel readout on one endcap
 - ▶ PID ($\pi - K - p$) from 100 MeV/c to 800 MeV/c
 - ▶ Tracking with large number of hits (pattern recognition)
 - ▶ Works only in barrel (field!)
- GridPIX
 - ▶ Avalanche grid in front of $55 \times 55 \mu\text{m}^2$ pixels.
 - ▶ >90% efficiency for single electrons.
 - ▶ Small area is not particularly expensive: 1800 chips (order/produce/test 3600) = \$716k
 - ▶ Careful: 1.2-5.4 kW of power
 - ▶ Services bulky: Gas, power, cooling
 - ▶ Realistic X/X_0 ?

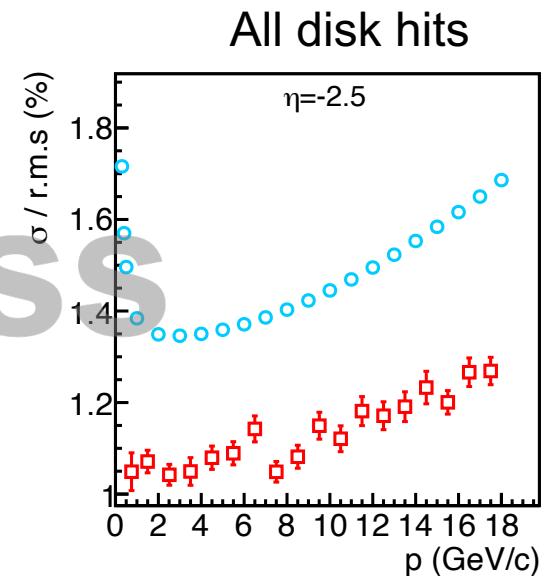
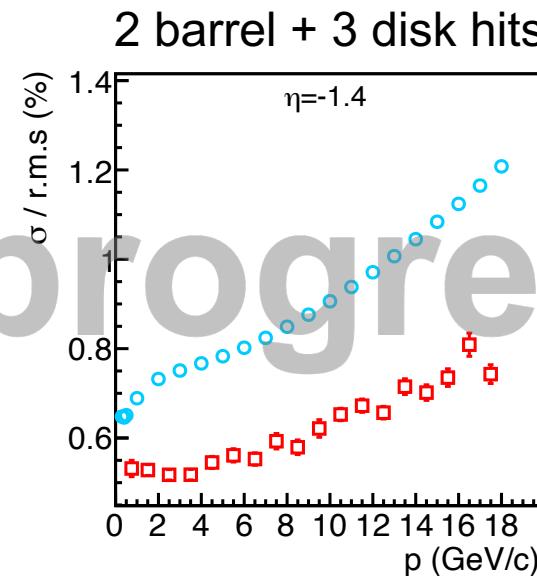
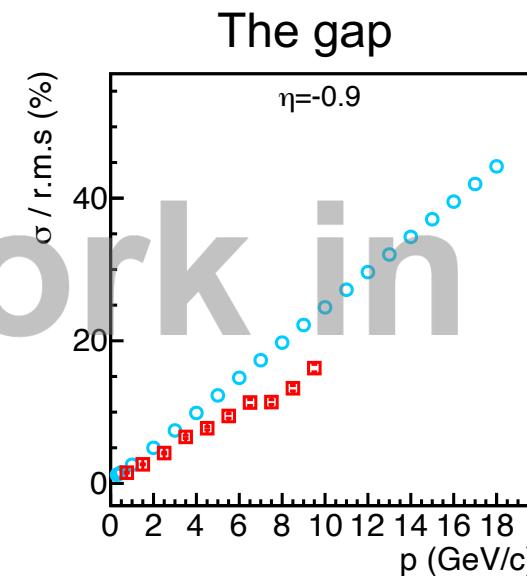
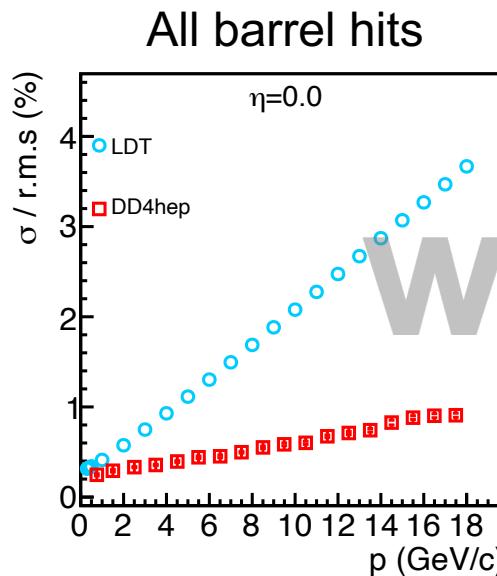
https://indico.bnl.gov/event/18414/contributions/76157/attachments/47563/80668/EIC_Technology_Inventory_Temple.pdf



- Reality check:
- Very compelling for D2
 - Provided tracking and dE/dx (compare with ToF/AC-LGAD)
 - Excellent Pattern recognition
 - Less sensitive to backgrounds
 - Generic R&D ongoing
 - Need to see concrete prototype

LDT Fast Simulation

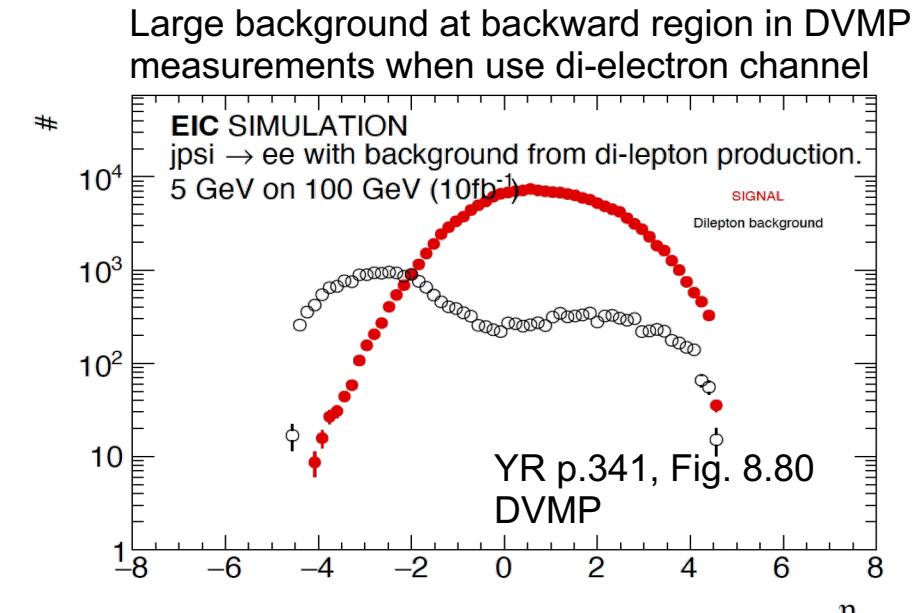
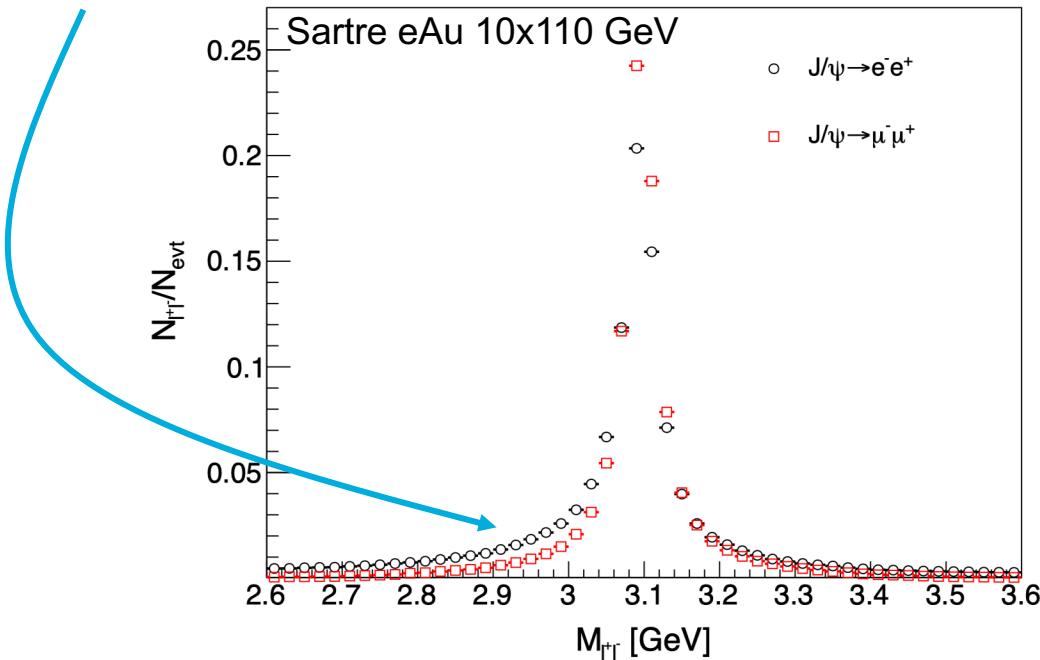
- ePIC craterlake silicon detector as baseline
 - Barrel: cylindrical, Silicon layers (option for TPC)
 - Forward/backward: Silicon disks
- Goals
 - Validating the LDT simulation
 - Implement TPC in the detector setup



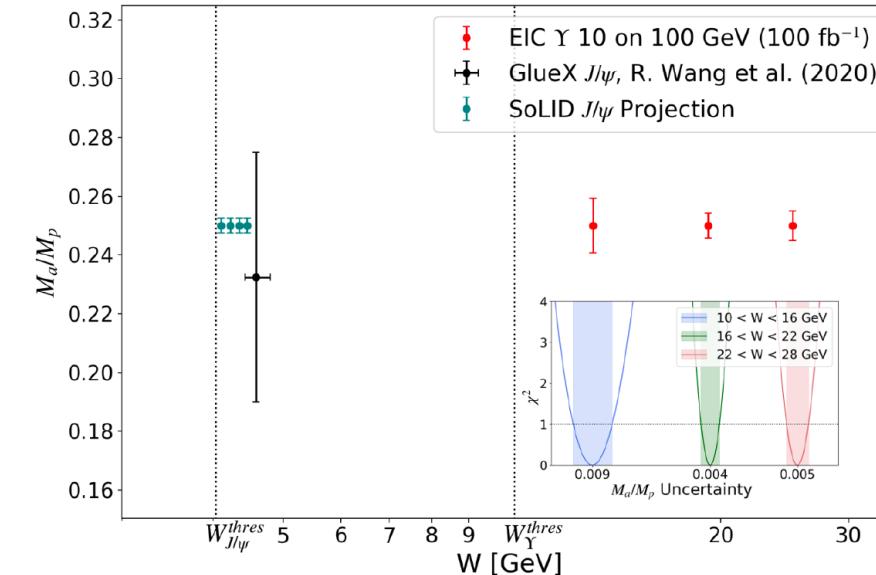
Muon ID

- Heavy quarkonia measurements → reduce ambiguity to the scattered electrons
- Complementary to and cross-checking with ePIC

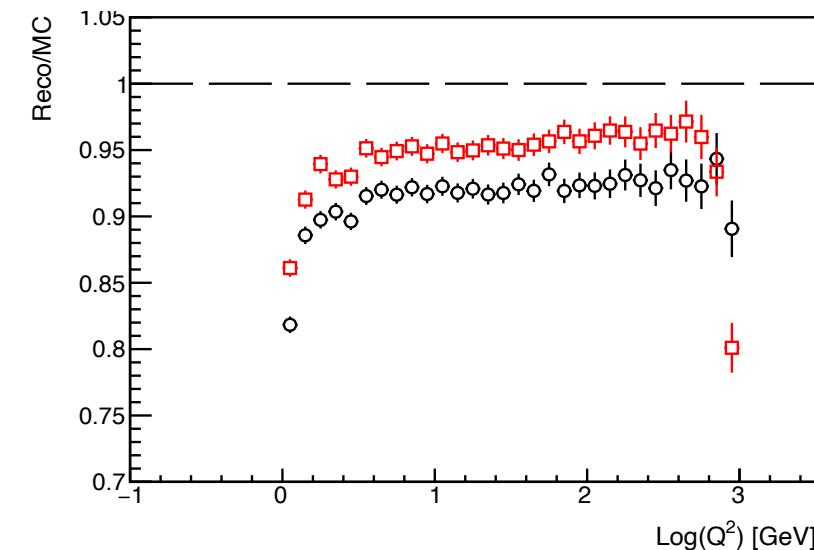
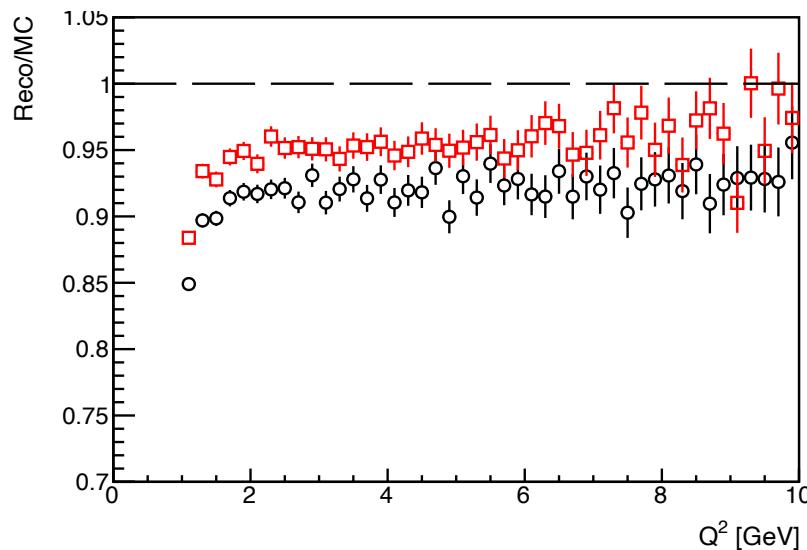
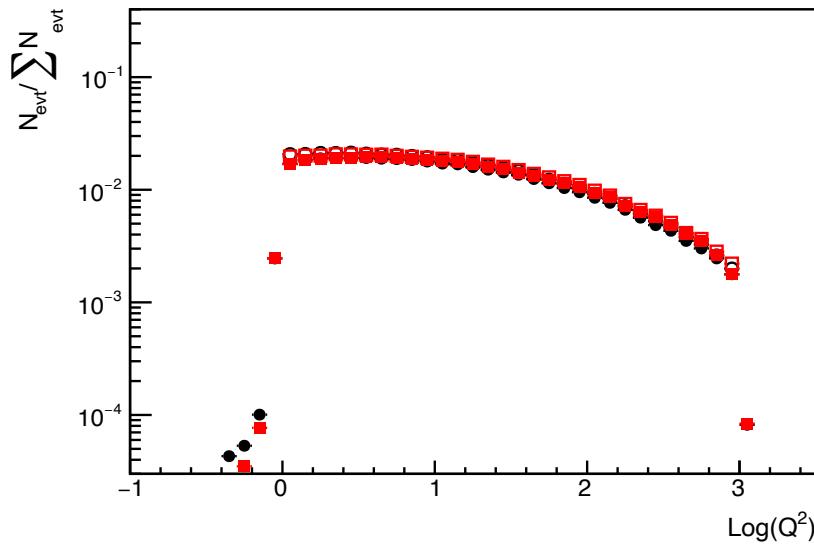
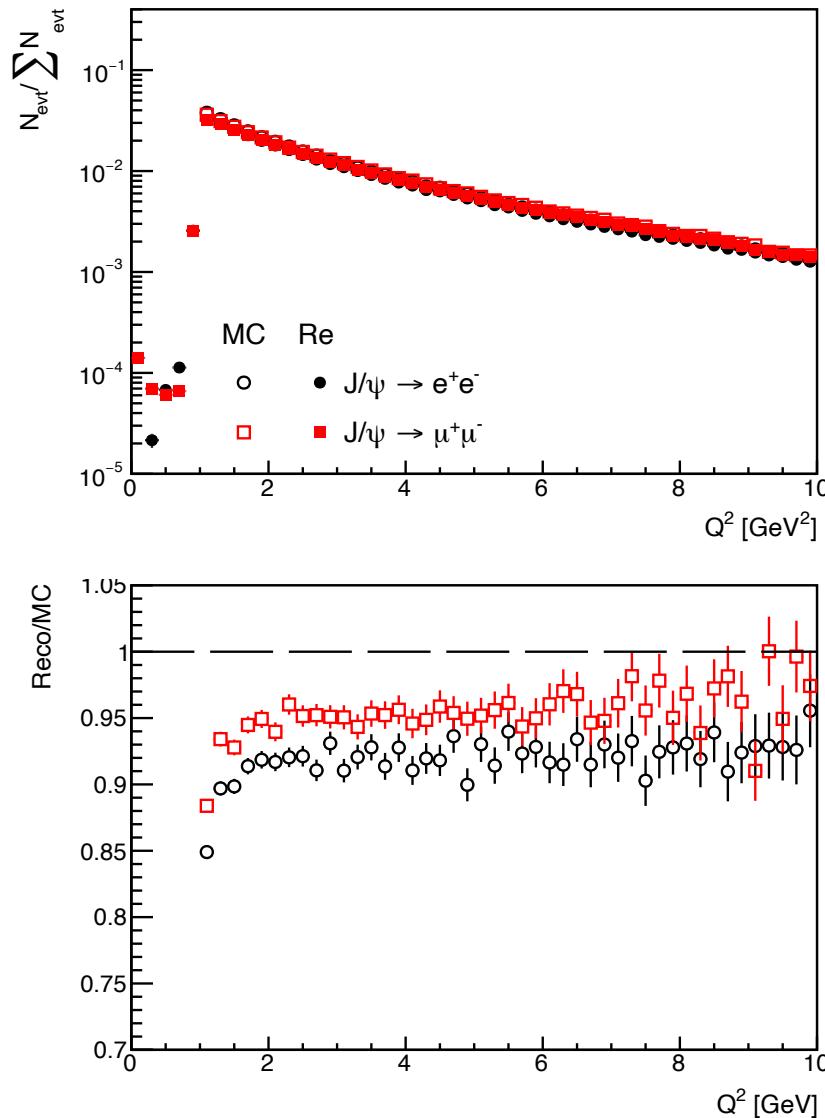
Larger combinatorial background at lower spectrum due to Bremsstrahlung radiation when using dielectron channel



In consideration: γ measurements at the EIC can extend the W coverage in trace anomaly study
(Challenge: require low p_T measurements)

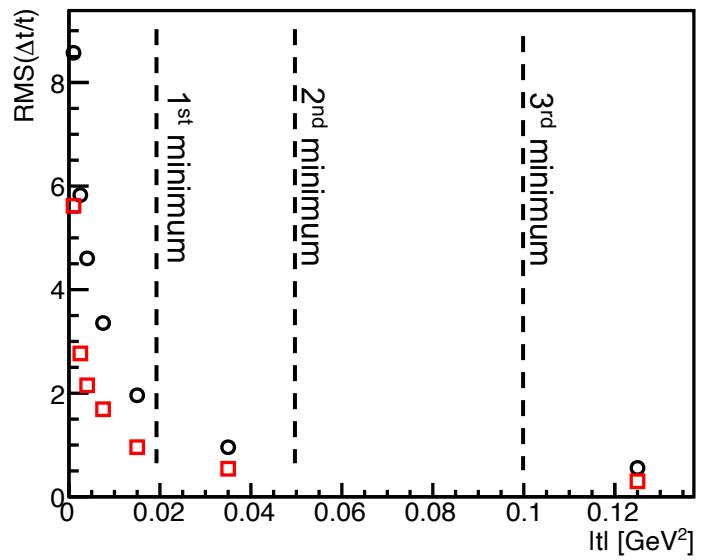
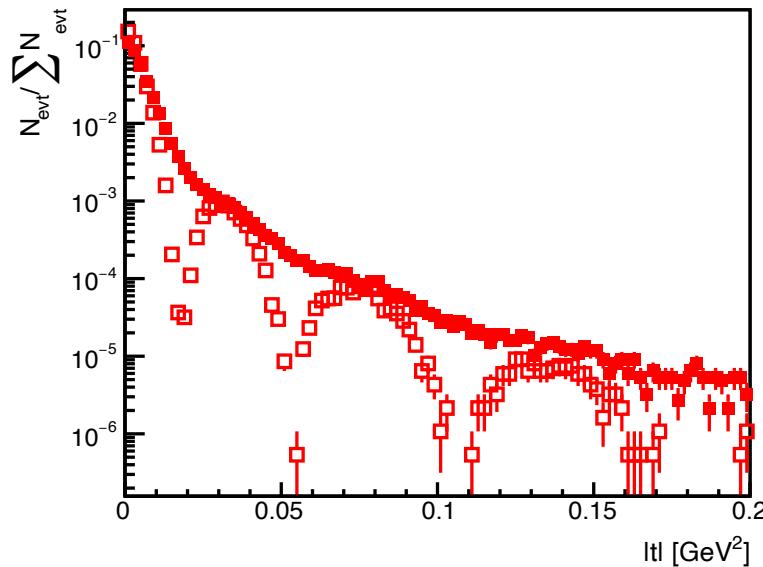
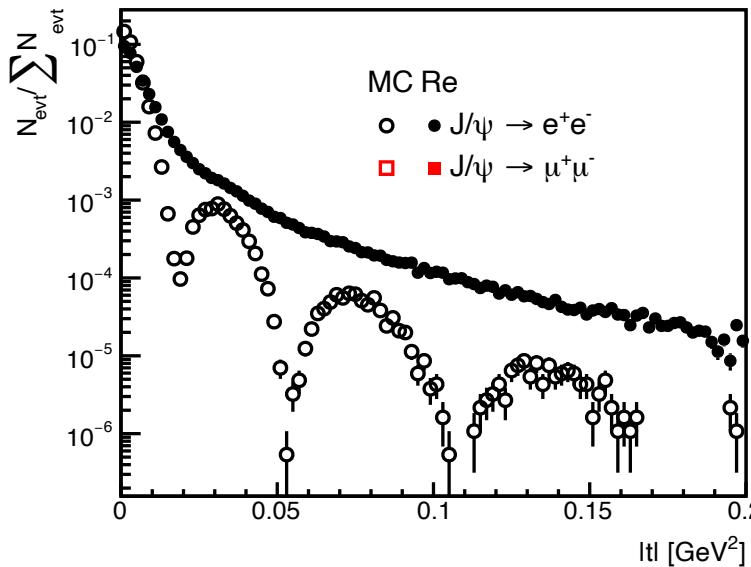


Reconstructed Q^2



- Using dielectron channel may reduce Q^2 efficiency since scattered electron could be mixed up as “ J/ψ decayed electron”

Reconstructed t



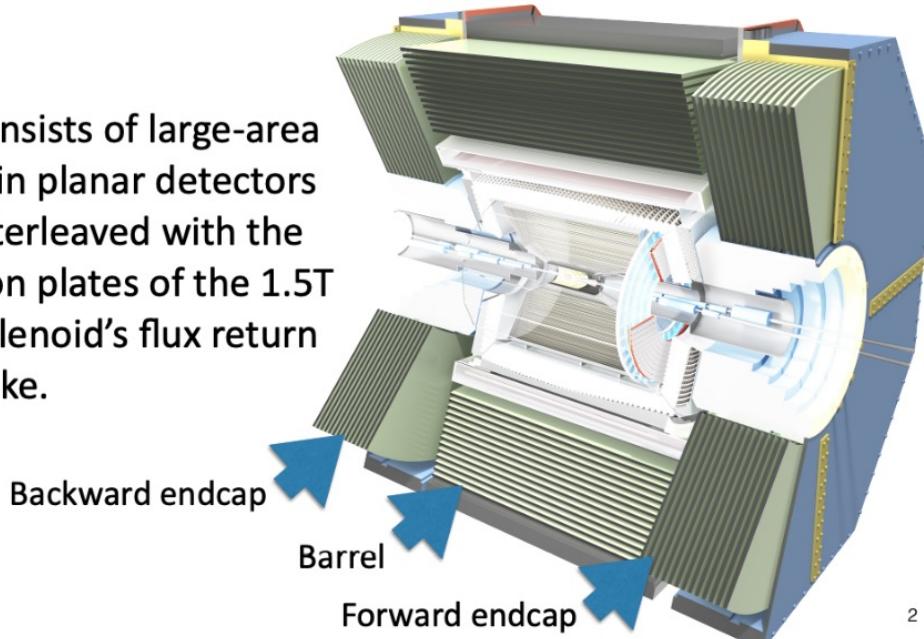
- Using dimuon channel improves the coherent J/ψ diffractive measurement compared to dielectron channel
 - Caveat: still using true PID in the above figures
- But improvement from using dimuon is not enough
 - Require significant improvement in scattered electron measurements
 - Beyond excellent backward tracking/Ecal with a momentum/energy resolution smaller than 1%

Example: K_L Muon Detector at BELLE II

EIC Generic R&D programs: #18 KLM-type detector

The KLM ("K_L-Muon detector")

consists of large-area thin planar detectors interleaved with the iron plates of the 1.5T solenoid's flux return yoke.



[https://doi.org/10.1016/S0168-9002\(99\)01383-2](https://doi.org/10.1016/S0168-9002(99)01383-2)

Belle Resistive Plate Counter

Ground plane	0.25 mm Mylar 0.035 mm Copper
Dielectric foam	7 mm
Cathode plane	0.035 mm Copper 0.25 mm Mylar 3.00 mm
+4.7 kV ► +HV	
-3.5 kV ► -HV	
Gas gap	2.00 mm
Insulator	0.5 mm Mylar
+4.7 kV ► +HV	3.00 mm
-3.5 kV ► -HV	
Gas gap	2.00 mm
Cathode plane	0.25 mm Mylar 0.035 mm Copper
Dielectric foam	7 mm
Ground plane	0.035 mm Copper 0.25 mm Mylar

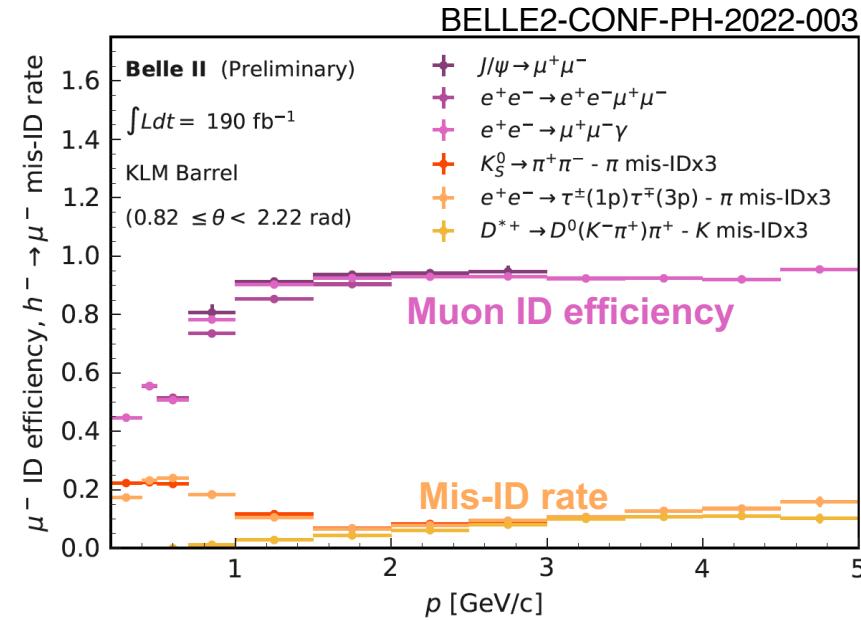
A detailed diagram of the Belle Resistive Plate Counter structure. It shows a stack of various components: Ground plane (0.25 mm Mylar, 0.035 mm Copper), Dielectric foam (7 mm), Cathode plane (0.035 mm Copper, 0.25 mm Mylar, 3.00 mm), Gas gap (2.00 mm), Insulator (0.5 mm Mylar), Cathode plane (+4.7 kV, +HV), Gas gap (2.00 mm), Insulator (-3.5 kV, -HV), Cathode plane (0.25 mm Mylar, 0.035 mm Copper), Dielectric foam (7 mm), and Ground plane (0.035 mm Copper, 0.25 mm Mylar). A vertical dashed blue line on the right indicates a total height of approximately 32 mm.

Glass-electrode resistive plate counters

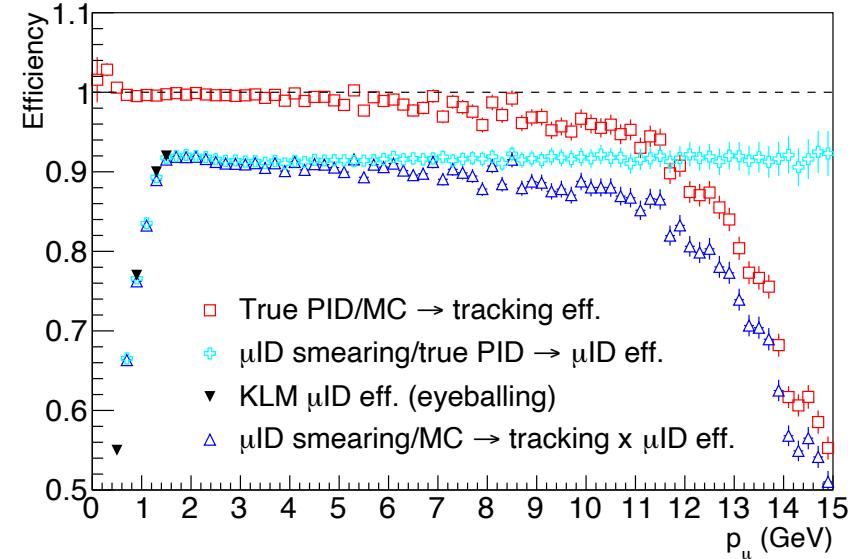
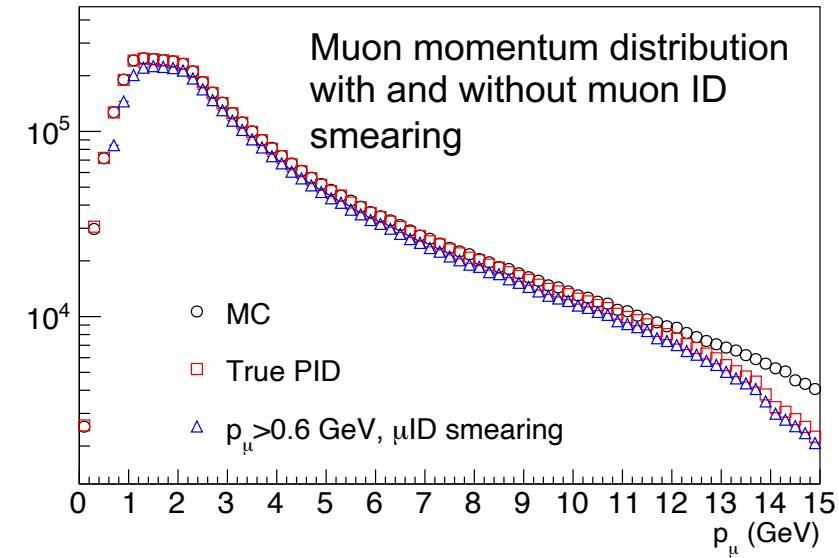
Muon Identification Smearing

Initial implementation using BELLE II KLM performance

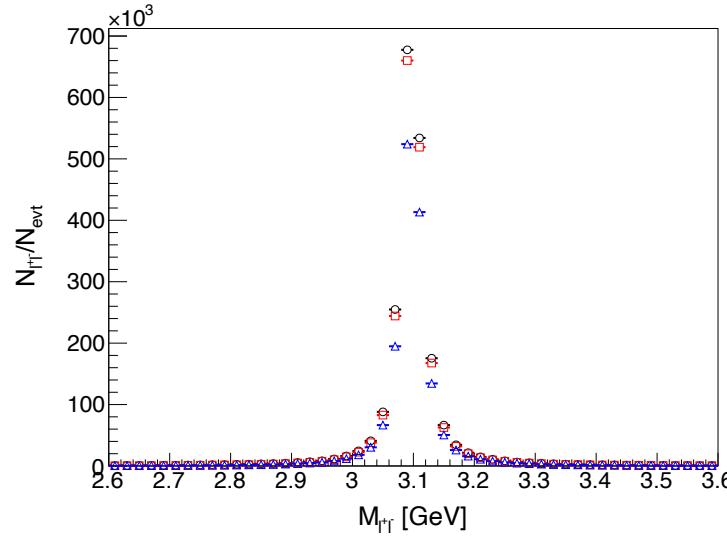
- Threshold momentum = 0.6 GeV
- Approximate muon ID efficiency at $p < 1.5$ GeV
- Constant muon ID efficiency at $p > 1.5$ GeV
- No mis-ID rate applied



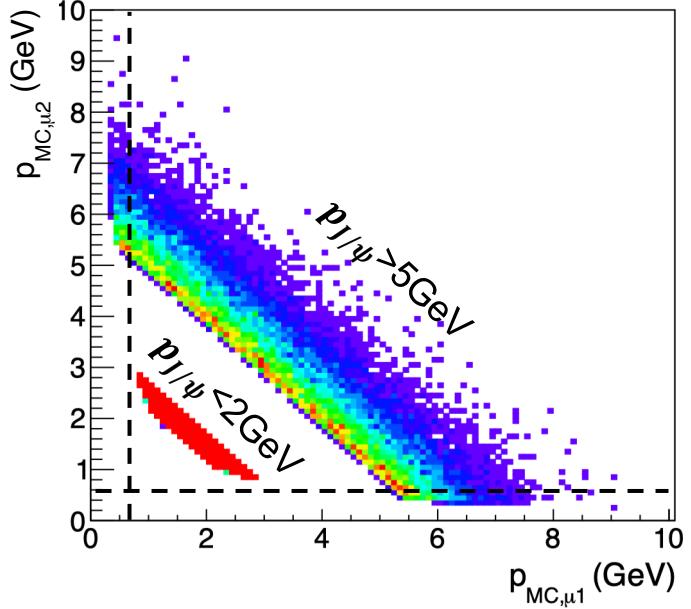
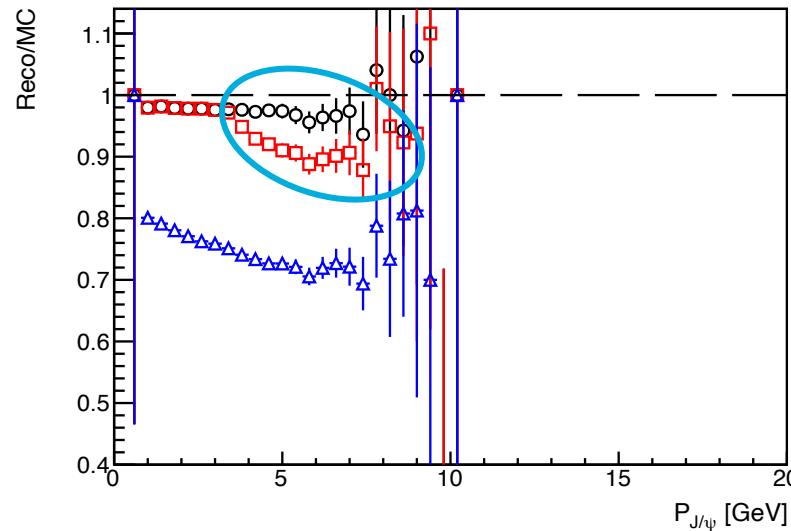
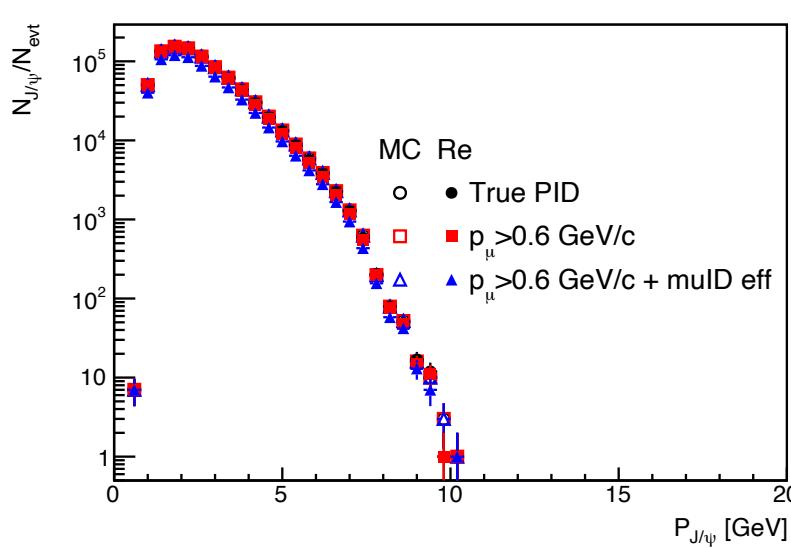
- https://docs.belle2.org/record/2895/files/Lepton_identification_Moriond_2022_v2.pdf
- <https://arxiv.org/pdf/1011.0352.pdf>



Reconstructed J/ψ with Muon ID Smearing

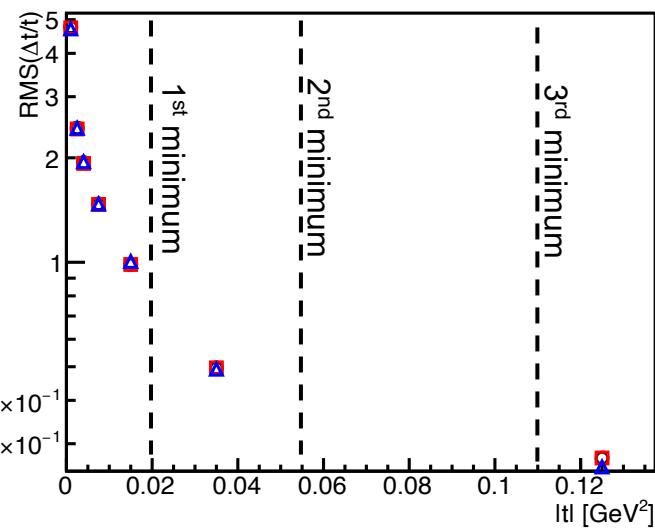
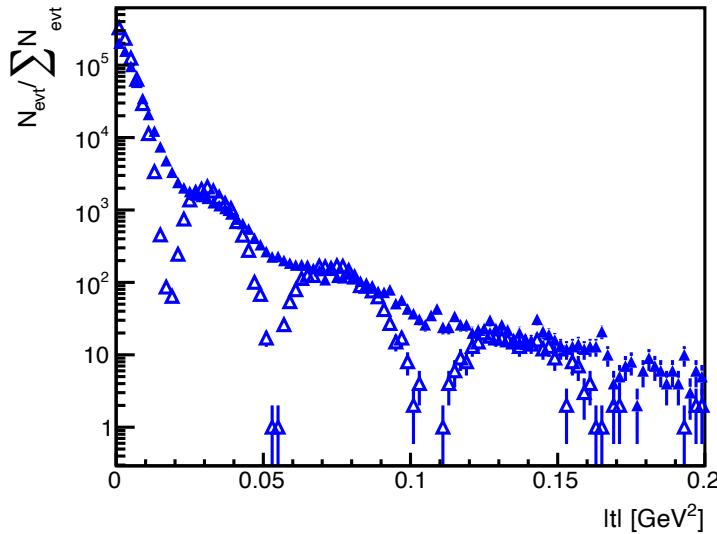
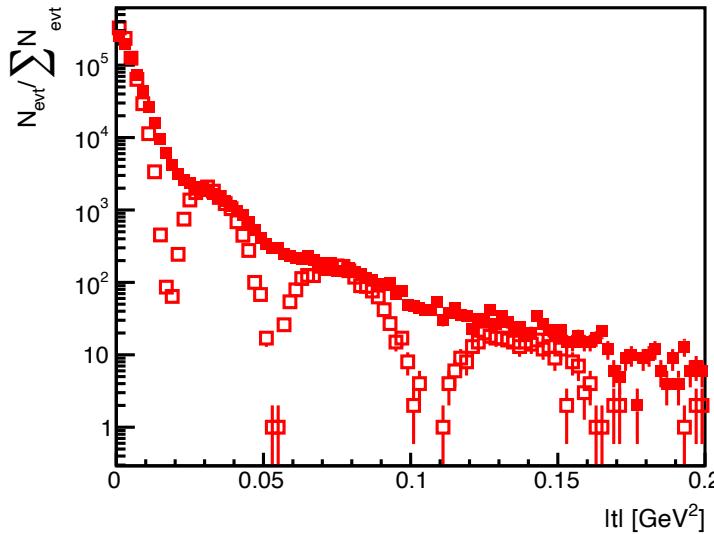
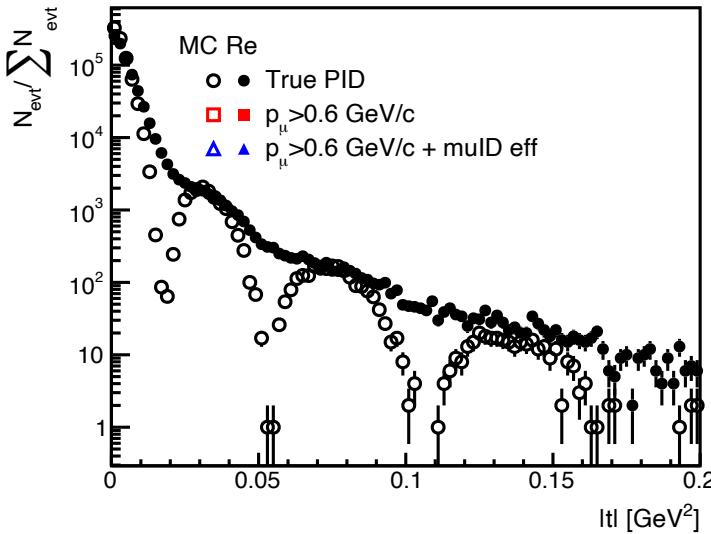


- Threshold muon momentum cut reduces reconstructed J/ψ at $p > 4$ GeV
- Statistics are reduced by 15-20% after μ ID efficiency implementation



Soft muon is important to high momentum J/ψ reconstruction

Reconstructed t ($1 \leq Q^2 \leq 10 \text{ GeV}^2$)



No significant changes in t resolutions from muon ID smearing

Summary

- Study mixed-tracking technologies design for the 2nd EIC detector
 - Reliable tracking and complementary to ePIC
 - LDT fast simulation
 - Working on simulation validation
 - Implement TPC
- Muon ID for quarkonia reconstruction
 - Reduce ambiguity to the scattered electrons and complementary to ePIC
 - Implement muon ID smearing using KLM performance